US00D826195S

(12) United States Design Patent

Podubni

(10) Patent No.: US D826,195 S
(45) Date of Patent: ** Aug. 21, 2018

(54) **MODULAR CIRCUIT BOARD**

(71) Applicant: **Tiny PCB, Inc.**, San Jose, CA (US)

(72) Inventor: **Edward Podubni**, San Jose, CA (US)

(73) Assignee: **TinyPCB, Inc.**

(**) Term: **15 Years**

(21) Appl. No.: **29/605,605**

(22) Filed: **May 26, 2017**

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 174/68.1, 250, 253, 255, 256; 318/567, 568.1; 361/600, 601, 718, 719, 361/720, 728, 736, 748, 751, 752, 760, 361/761, 807; 439/55, 65, 68, 76.1, 92, 439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301; H05K 3/303; H05K 3/34; H05K 3/3405; H05K 3/341; H05K 3/36; H05K 3/361; H05K 3/363; H05K 3/40; H05K 7/14; H05K 7/1422; H05K 7/00; H05K 1/18; H05K 1/02; H05K 1/181; H05K 1/182; H05K 1/183; H05K 1/184; H05K 1/189; H05K 1/00
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2,896,033	A *	7/1959	Hartz	H01H 19/585	200/11 D
3,072,734	A *	1/1963	Fox	H02B 1/043	174/254
D279,670	S *	7/1985	Lukits	D13/182	
4,602,271	A *	7/1986	Dougherty, Jr.	H01L 23/5385	257/697
4,715,928	A *	12/1987	Hamby	H05K 3/4691	156/150
D319,045	S *	8/1991	Hasegawa	D13/182	
D319,629	S *	9/1991	Hasegawa	D13/182	
D319,814	S *	9/1991	Hasegawa	D13/182	
D397,093	S *	8/1998	Kim	D13/182	
5,895,967	A *	4/1999	Stearns	H01L 23/3128	257/691
D429,704	S *	8/2000	Kang	D13/182	
6,121,554	A *	9/2000	Kamikawa	H05K 1/113	174/255
D440,209	S *	4/2001	Kang	D13/182	
D442,149	S *	5/2001	Kang	D13/182	
D442,150	S *	5/2001	Kang	D13/182	
D442,567	S *	5/2001	Kang	D13/182	
D457,146	S *	5/2002	Yamamoto	D13/182	
6,418,030	B1 *	7/2002	Yamaguchi	H01L 23/24	257/698
6,462,570	B1	10/2002	Price et al.		
D466,093	S *	11/2002	Ebihara	D13/182	
D471,167	S *	3/2003	Ebihara	D13/182	

(Continued)

Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Cooley LLP

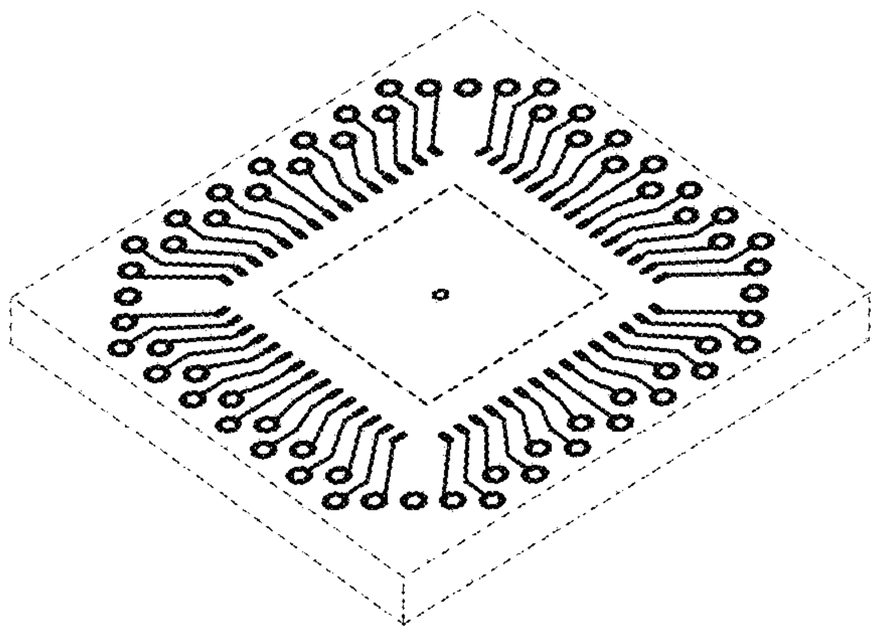
(57) **CLAIM**

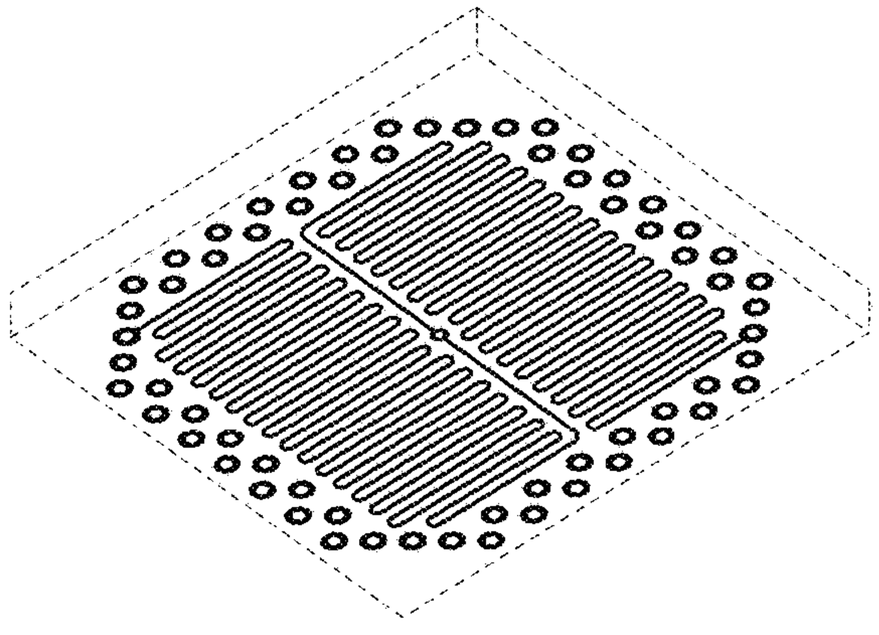
The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a modular circuit board, showing my new design;
FIG. **2** is a bottom perspective view thereof;
FIG. **3** is a top view thereof;
FIG. **4** is a bottom view thereof; and,
FIG. **5** is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets





(56) **References Cited**

U.S. PATENT DOCUMENTS

D474,773	S *	5/2003	Kondo	D13/182
D485,536	S *	1/2004	Dang	D13/182
6,936,916	B2 *	8/2005	Moxham	H01L 23/13 174/256
D552,048	S *	10/2007	He	D13/182
D556,158	S *	11/2007	Kong	D13/182
7,511,228	B2	3/2009	Yaung et al.	
D599,308	S *	9/2009	Blumberg, Jr.	D13/182
D605,613	S *	12/2009	Carter	D13/182
D639,756	S *	6/2011	Greene, Jr.	D13/182
D642,546	S *	8/2011	Greene, Jr.	D13/182
D645,039	S *	9/2011	Chen	D14/341
8,113,888	B2 *	2/2012	Carter	H01R 9/03 439/676
D676,004	S *	2/2013	Lyubachev	D13/182
D699,201	S *	2/2014	Petsch	D13/182
D768,115	S *	10/2016	Kazanchian	D13/182
D794,586	S *	8/2017	Takahashi	D13/182
D799,438	S *	10/2017	Takahashi	D13/182
D804,437	S *	12/2017	Kantor	D13/182
2006/0044765	A1 *	3/2006	Chen	H05K 1/0206 361/720
2007/0205017	A1 *	9/2007	Takakusaki	H05K 3/244 174/260
2008/0080151	A1 *	4/2008	Shimizu	H05K 1/0263 361/760
2009/0250246	A1	10/2009	Yaung et al.	
2009/0268390	A1 *	10/2009	King	G06F 13/409 361/679.33

* cited by examiner

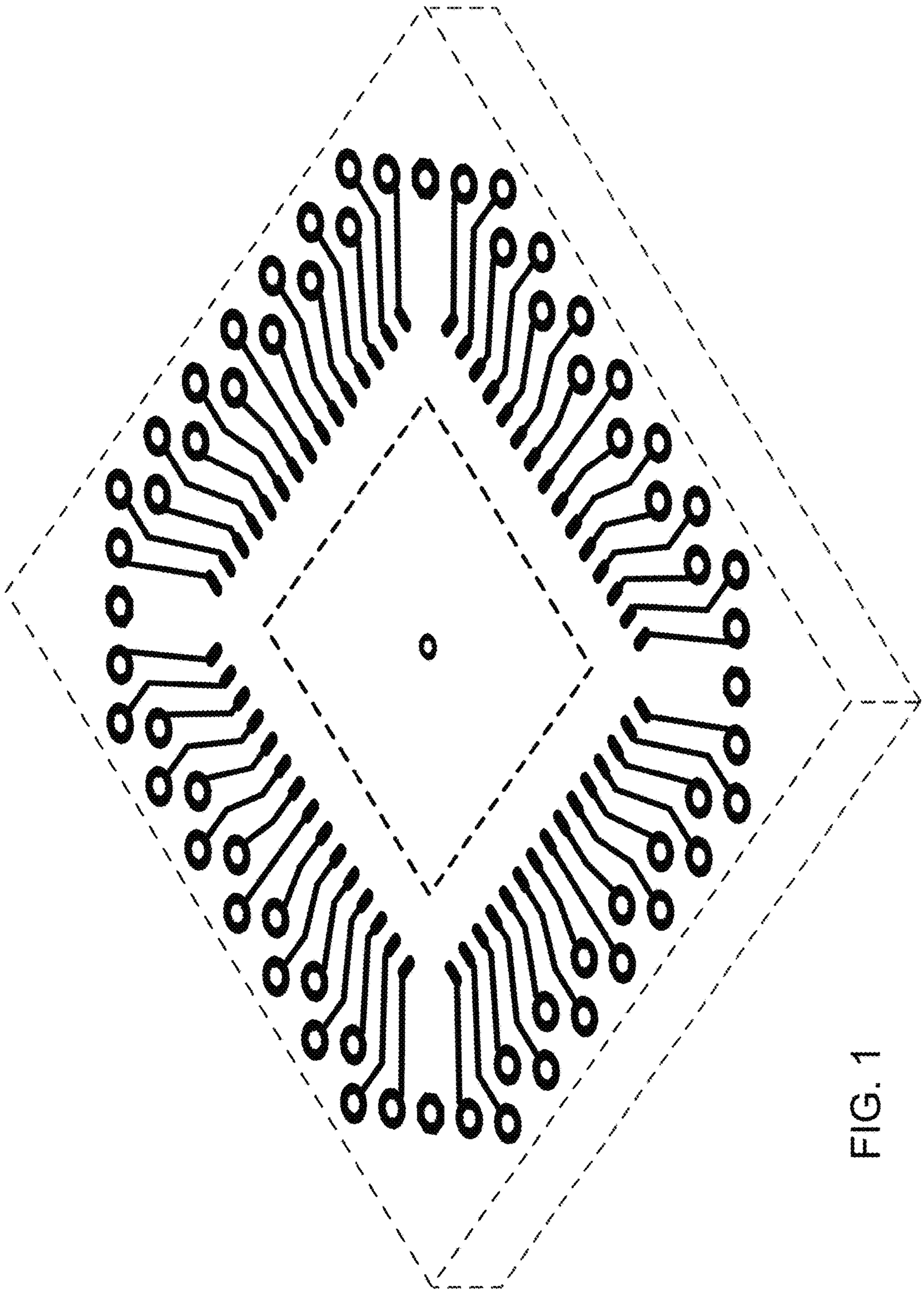


FIG. 1

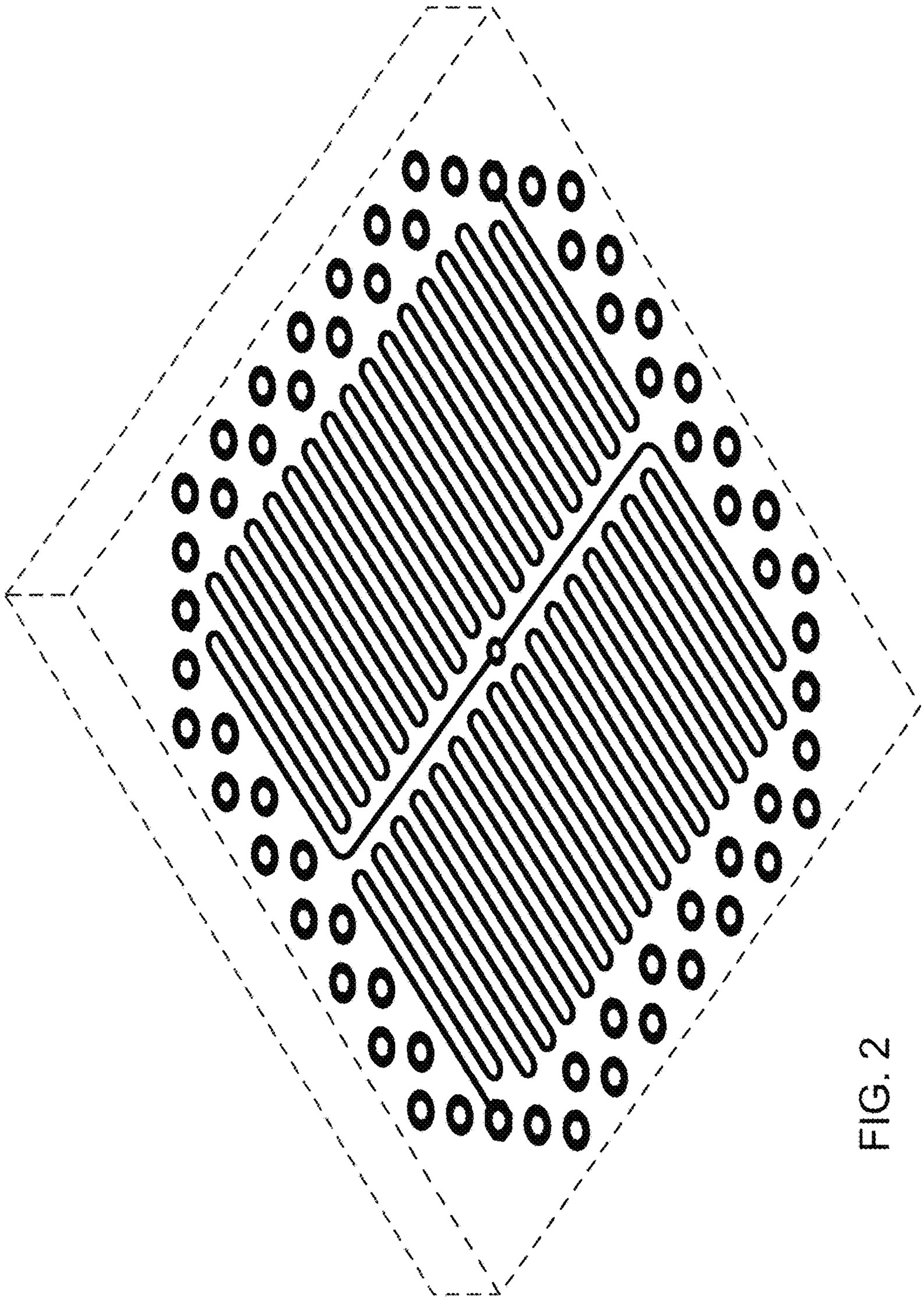


FIG. 2

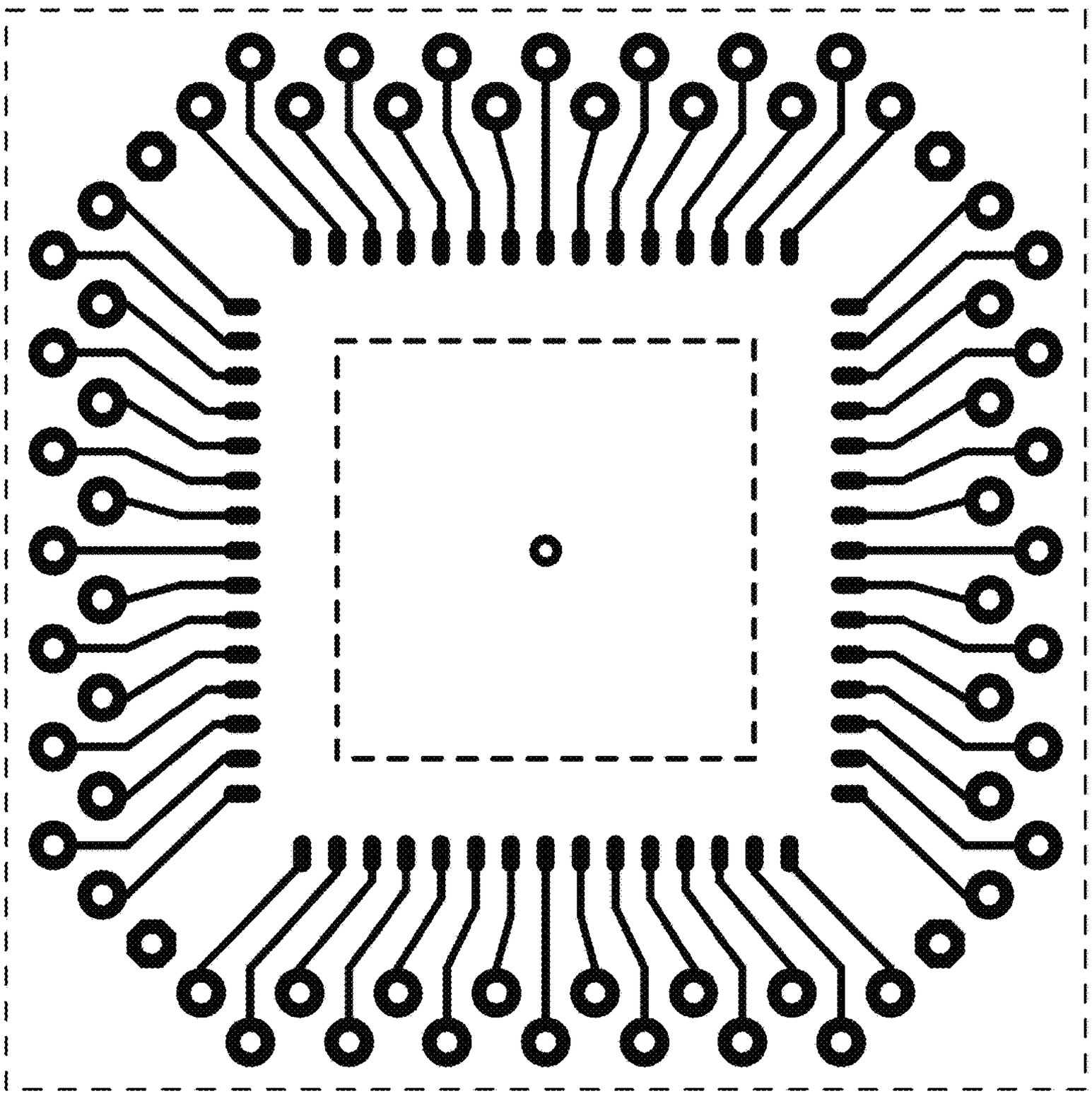


FIG. 3

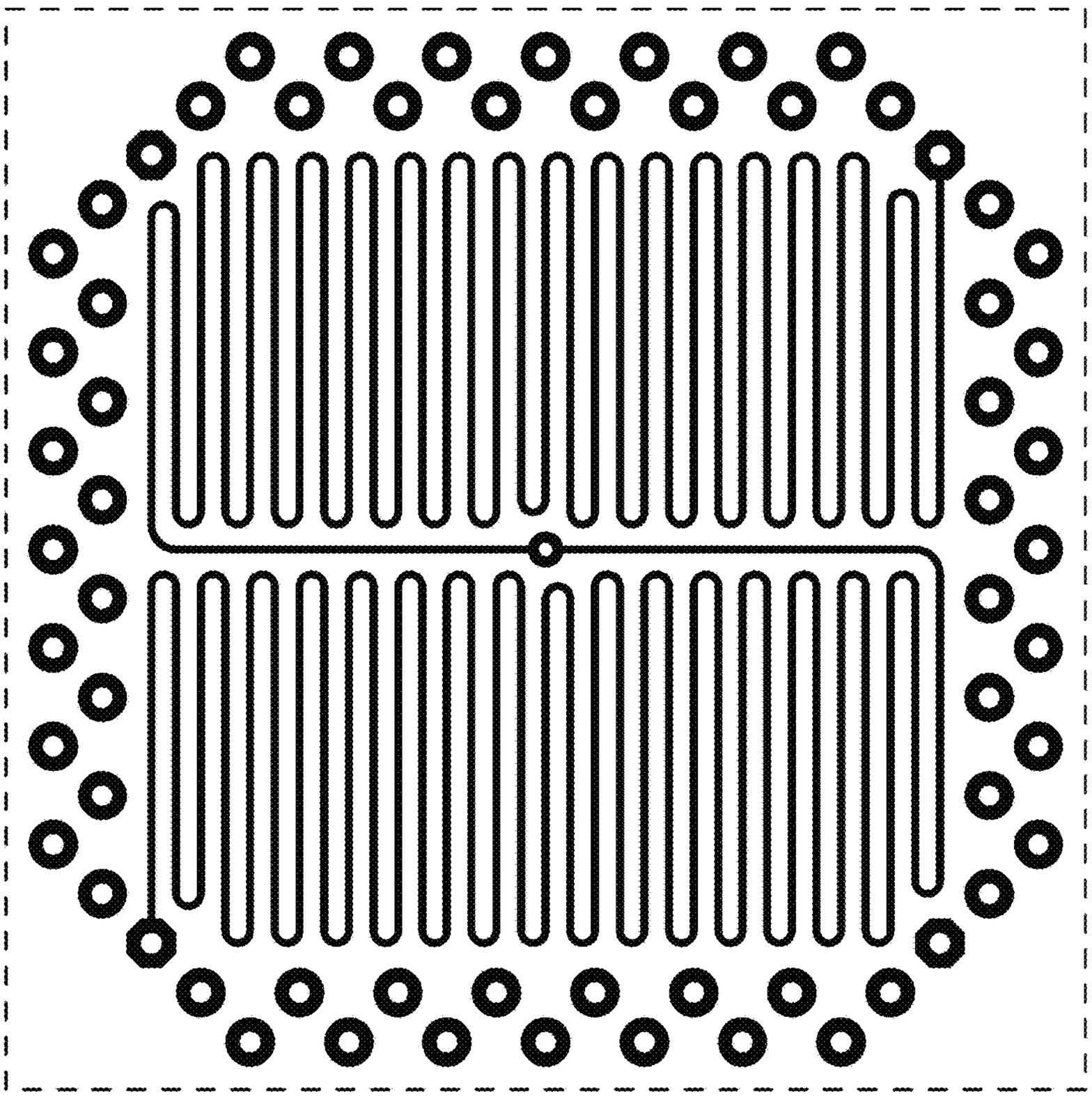


FIG. 4

FIG. 5